SLLS178D - APRIL 1994 - REVISED FEBRUARY 2000

● Single-Chip and Single-Supply Interface for IBM PC/AT <sup>™</sup> Serial Port	DB PACKAGE <sup>†</sup> (TOP VIEW)
<ul> <li>Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.11 Standards</li> </ul>	V <sub>DD</sub> [ 1 28 ] C3+ C2+ [ 2 27 ] GND
Operates With 3.3-V or 5-V Supplies	$V_{CC}$ [ 3 26 ] C3-
One Receiver Remains Active During	C2- [] 4 25 [] V <sub>SS</sub>
Standby (Wake-up Mode)	EN 5 24 C1-
Designed to Operate at 128 kbit/s Over a	C1+ 6 23 STBY
3-m Cable	
Low Standby Current 5 μA Max	DIN2 [ 8 21 ] DOUT2 DIN3 [ 9 20 ] DOUT3
ESD Protection on RS-232 Pins Meets or	ROUT1 [] 10 19 [] RIN1
Exceeds 4 kV (HBM) and 1.5 kV (HBM) on	ROUT2 11 18 RIN2
All Pins Per MIL-STD-883, Method 3015	ROUT3 🛛 12 17 🗍 RIN3
• External Capacitors 0.1 μF	ROUT4 🛛 13 16 🗍 RIN4
(V <sub>CC</sub> = 3.3 V Five External Capacitors) (V <sub>CC</sub> = 5 V Four External Capacitors)	ROUT5 14 15 RIN5
Accepts 5-V Logic Input With 3.3-V Supply	<sup>†</sup> The DB package is only
Applications	available in left-ended tape and
- RS-232 Interface	reel (order part number SN75LV4737ADBR).
<ul> <li>Battery-Powered Systems, PDAs</li> </ul>	/

- Notebook, Laptop, and Palmtop PCs
- External Modems and Hand-Held Terminals
- Packaged in Shrink Small-Outline Package

#### description

The SN75LV4737A<sup>‡</sup> consists of three line drivers, five line receivers, and a charge-pump circuit. It provides the electrical interface between an asynchronous communication controller and the serial-port connector, and meets the requirements of TIA/EIA-232-F. This combination of drivers and receivers matches those needed for the typical serial port used in an IBM PC/AT or compatibles. The charge pump and five small external capacitors allow operation from a single 3.3-V supply, and four capacitors allow operation from a 5-V supply.

The device has flexible control options for power management when the serial port is inactive. A common disable for all of the drivers and receivers is provided with the active-high STBY input. The active-low  $\overline{EN}$  input is an enable for one receiver to implement a wake-up feature for the serial port. All the logic inputs can accept signals from controllers operating from a 5-V supply, even though the SN75LV4737A is operating from 3.3 V.

The SN75LV4737A is characterized for operation over the temperature range of 0°C to 70°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

<sup>‡</sup> Patent-pending design IBM and PC/AT are trademarks of International Business Machines Corporation.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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#### SLLS178D - APRIL 1994 - REVISED FEBRUARY 2000

#### **Function Tables**

FACH	DRIVER
LAOII	

INP	UTS	OUTPUT
DIN	STBY	DOUT
Х	Н	Z
L	L	н
н	L	L
Open	L	L
H = high	n level, L	= low level,

X = irrelevant, Z = high impedance

#### EACH RECEIVER

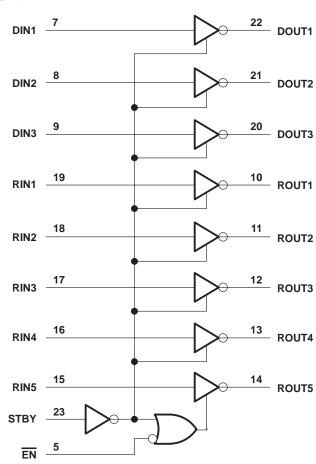
		INPUTS	OUTPUTS				
STBY	EN	RIN5	RIN1-RIN4	ROUT5	ROUT1-ROUT4		
Н	Н	Х	Х	Z	Z		
н	L	Н	Х	L	Z		
н	L	L	х	н	Z		
L	Х	L	L	н	Н		
L	Х	Н	Н	L	L		

H = high level, L = low level, X = irrelevant, Z = high impedance



SLLS178D - APRIL 1994 - REVISED FEBRUARY 2000

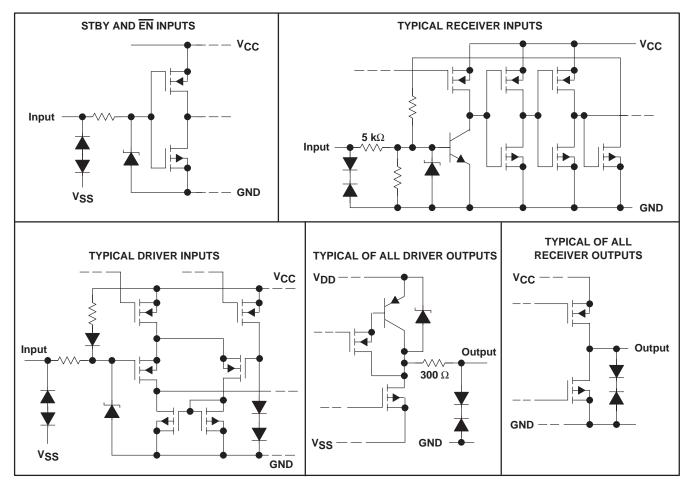
# logic diagram (positive logic)





SLLS178D – APRIL 1994 – REVISED FEBRUARY 2000

### schematics of inputs and outputs



#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage, V <sub>CC</sub>	
Positive output supply voltage, V <sub>DD</sub> (see Note 1)	15 V
Negative output supply voltage, V <sub>SS</sub>	–15 V
Input voltage range, V <sub>I</sub> : Driver	
Receiver	
Output voltage range, V <sub>O</sub> : Driver	
Receiver	–0.3 V to 7 V
Package thermal impedance, $\theta_{JA}$ (see Note 2)	
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	
Storage temperature range, T <sub>stg</sub>	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to network GND.

2. The package thermal impedance is calculated in accordance with JESD 51.



SLLS178D - APRIL 1994 - REVISED FEBRUARY 2000

#### recommended operating conditions

				MIN	NOM	MAX	UNIT
Vaa	Supply voltage		V <sub>CC</sub> = 3.3 V	3	3.3	3.6	V
Vcc	Supply voltage		$V_{CC} = 5 V$	4.5	5	5.5	V
		DIN, EN, STBY	V <sub>CC</sub> = 3.3 V	2			
VIH	Driver high-level input voltage	DIN		2			V
		EN, STBY	V <sub>CC</sub> = 5 V	2.5			1
VIL	Driver low-level input voltage	DIN, EN, STBY				0.8	V
VI	Receiver input voltage					±30	V
	External capacitor	3.3-V operation (C1, C2, C3, C4, C5), 5-V operation (C1, C3, C4, C5), See Note 3 and Figures 6 and 7		0.1			μF
TA	Operating free-air temperature	•		0		70	°C

NOTE 3: C2 is needed only for 3.3-V operation.

# electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (see Figures 6 and 7) (unless otherwise noted)

	PARAMETER		TEST CONDITIONS		V <sub>CC</sub> = 3.3 V			V <sub>CC</sub> = 5 V		
	FARAMETER	1231			TYP†	MAX	MIN	TYP†	MAX	UNIT
VDD	Positive supply voltage	No load		8	10		7	8.7		V
VSS	Negative supply voltage	No load			-9.5	-7		-8	-6	V
Ц	Input current (EN, STBY)	See Notes 4 and 5				±2			±2	μΑ
	Supply current		STBY at GND, EN at V <sub>CC</sub> or GND	8.4	10	18	10	12	20.7	mA
ICC	Supply current (standby mode) (see Note 4)	No load, Inputs open	$\overline{\text{EN}}$ , STBY at V <sub>CC</sub>			5			5	۵
	Supply current (wake-up mode) (see Note 5)		EN at GND, STBY at V <sub>CC</sub>			10			10	μA

<sup>†</sup> All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

NOTES: 4. When standby mode is not used, STBY input must be taken low.

5. When wake-up mode is not used, EN input must be taken high.



SLLS178D – APRIL 1994 – REVISED FEBRUARY 2000

## DRIVER SECTION

# electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS			TYP†	MAX	UNIT
VOH	High-level output voltage	$R_L = 3 k\Omega$		5.5	7		V
VOL	Low-level output voltage	$R_L = 3 k\Omega$			-6	-5	V
Ιн	High-level input current	$A^{I} = A^{CC}$				1	μΑ
۱ <sub>IL</sub>	Low-level input current	V <sub>I</sub> at GND				-10	μΑ
100	Short-circuit output current (see Note 6)	V <sub>CC</sub> = 3.6 V,	VO = 0 V		±15	+40	mA
los	Shon-circuit output current (see Note 6)	V <sub>CC</sub> = 5.5 V,	VO = 0 V		±15	±40	ША
r <sub>o</sub>	Output resistance	$V_{CC} = V_{DD} = V_{SS} = 0 V,$	$V_{O} = \pm 2 V$	300	500		Ω

<sup>†</sup> All typical values are at  $V_{CC}$  = 3.3 V or  $V_{CC}$  = 5 V, and  $T_A$  = 25°C.

NOTE 6: Short-circuit durations should be controlled to prevent exceeding the device absolute maximum power dissipation ratings, and not more than one output should be shorted at a time.

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CO	NDITIONS	MIN	TYP†	MAX	UNIT
	Propagation delay time, low- to high-level output		V <sub>CC</sub> = 3.3 V	100	500	850	ns
<sup>t</sup> PLH	Propagation delay time, low- to high-level output	$C_{L} = 50 \text{ pF},$	$V_{CC} = 5 V$	100	500	850	115
+	Propagation delay time, high- to low-level output	$R_L = 3 k\Omega$ to 7 k $\Omega$ , See Figure 1	V <sub>CC</sub> = 3.3 V	100	500	850	ns
<sup>t</sup> PHL	Propagation delay time, high- to low-level output	Ũ	$V_{CC} = 5 V$	100	500	850	115
<sup>t</sup> PZH	Output enable time to high level	C <sub>L</sub> = 50 pF,	$R_L = 3 k\Omega$ to 7 k $\Omega$ ,		1	5	ms
<sup>t</sup> PZL	Output enable time to low level	See Figure 2			3	7	ms
to	Output disable time from high level		V <sub>CC</sub> = 3.3 V		0.9	3	
<sup>t</sup> PHZ	Output disable time nom nightever	$C_L = 50 \text{ pF},$	$V_{CC} = 5 V$		0.6	3	μs
t = 1 =	Output disable time from low level	$R_L = 3 k\Omega$ to 7 k $\Omega$ , See Figure 2	V <sub>CC</sub> = 3.3 V		0.5	3	
<sup>t</sup> PLZ	Output disable time from low level	Ű	$V_{CC} = 5 V$		0.3	3	μs
SR	Slew rate	C <sub>L</sub> = 50 pF, See Figure 1	$R_L = 3 k\Omega$ to 7 k $\Omega$ ,	4		30	V/µs
SR(tr)	Slew rate, transition region	C <sub>L</sub> = 2500 pF, See Figure 3	$R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega$ ,	3		30	V/µs

<sup>†</sup> All typical values are at  $V_{CC}$  = 3.3 V or  $V_{CC}$  = 5 V, and  $T_A$  = 25°C.



SLLS178D - APRIL 1994 - REVISED FEBRUARY 2000

### **RECEIVER SECTION**

# electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CONE	TEST CONDITIONS			MAX	UNIT
VOH	High-level output voltage	I <sub>OH</sub> = -2 mA	V <sub>CC</sub> = 3.3 V	2.4	3		V
VOH	high-level output voltage	OH = -2 IIIA	$V_{CC} = 5 V$	3.5	5		v
VOL	Low-level output voltage	$I_{OL} = 2 \text{ mA}$		0.2	0.4	V	
VIT+	Positive-going input threshold voltage				2.2	2.6	V
V <sub>IT</sub>	Negative-going input threshold voltage			0.6	1		V
V <sub>hys</sub>	Input hysteresis (V <sub>IT+</sub> – V <sub>IT</sub> _)			0.5	1.2	1.8	V
ri	Input resistance	$V_{I} = \pm 3 V \text{ to } \pm 25 V$		3	5	7	kΩ

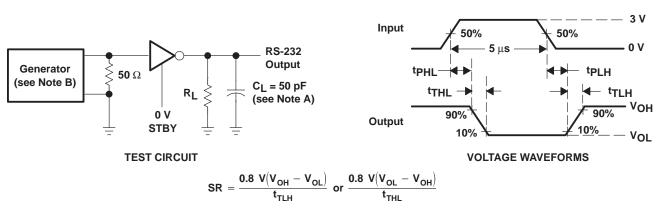
<sup>†</sup> All typical values are at  $V_{CC}$  = 3.3 V or  $V_{CC}$  = 5 V, and  $T_A$  = 25°C.

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C<sub>L</sub> = 50 pF, R<sub>L</sub> = 3 k $\Omega$ to GND

	PARAMETER	TEST	۷c	C = 3.3	V	V	CC = 5 V	1	UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	UNIT
<sup>t</sup> PLH	Propagation delay time, low- to high-level output		10	70	200	10	70	200	ns
<sup>t</sup> PHL	Propagation delay time, high- to low-level output	]	10	60	200	10	55	200	ns
<sup>t</sup> PLH	Propagation delay time, low- to high-level output (wake-up mode)	See Figure 4		40	200		40	200	μs
<sup>t</sup> PHL	Propagation delay time, high- to low-level output (wake-up mode)			90	500		70	500	ns
<sup>t</sup> PZH	Output enable time to high level			3	10		1.2	10	μs
<sup>t</sup> PZL	Output enable time to low level	Soo Eiguro E		100	250		60	250	ns
<sup>t</sup> PHZ	Output disable time from high level	See Figure 5	100	200	600	100	150	600	ns
<sup>t</sup> PLZ	Output disable time from low level			130	250		60	250	ns



SLLS178D - APRIL 1994 - REVISED FEBRUARY 2000

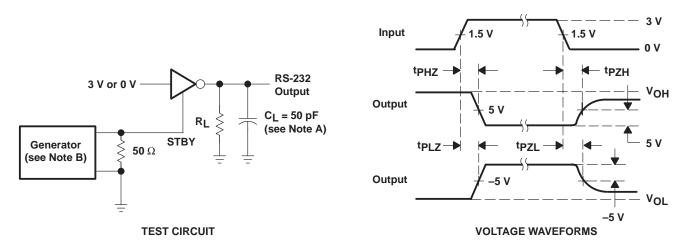


### PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

B. The pulse generator has the following characteristics:  $Z_0 = 50 \Omega$ , 50% duty cycle,  $t_f \le 10$  ns.  $t_f \le 10$  ns.

#### Figure 1. Driver Propagation Delay Times and Slew Rate (5-µs Input)



NOTES: A.  $C_L$  includes probe and jig capacitance.

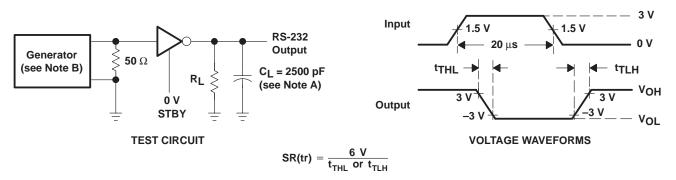
B. The pulse generator has the following characteristics:  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_f \le 10$  ns.  $t_f \le 10$  ns.

#### Figure 2. Driver Enable and Disable Test Times



SLLS178D - APRIL 1994 - REVISED FEBRUARY 2000

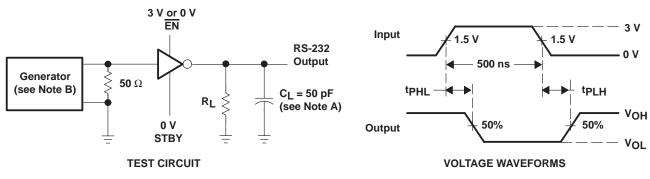
### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

B. The pulse generator has the following characteristics:  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_f \le 10$  ns.  $t_f \le 10$  ns.

#### Figure 3. Driver Transition Times and Slew Rate (20-µs Input)

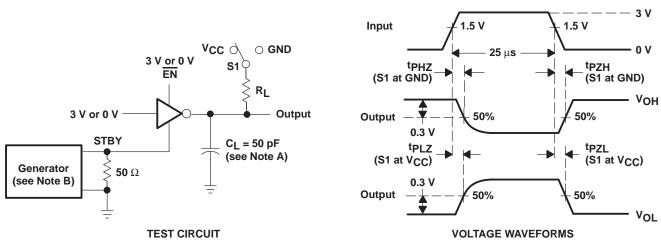


NOTES: A. C<sub>L</sub> includes probe and jig capacitance. B. The pulse generator has the following characteristics: PRR = 1 MHz,  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_f \le 10$  ns.  $t_f \le 10$  ns.

**Figure 4. Receiver Propagation Delay Times** 



SLLS178D – APRIL 1994 – REVISED FEBRUARY 2000



### PARAMETER MEASUREMENT INFORMATION

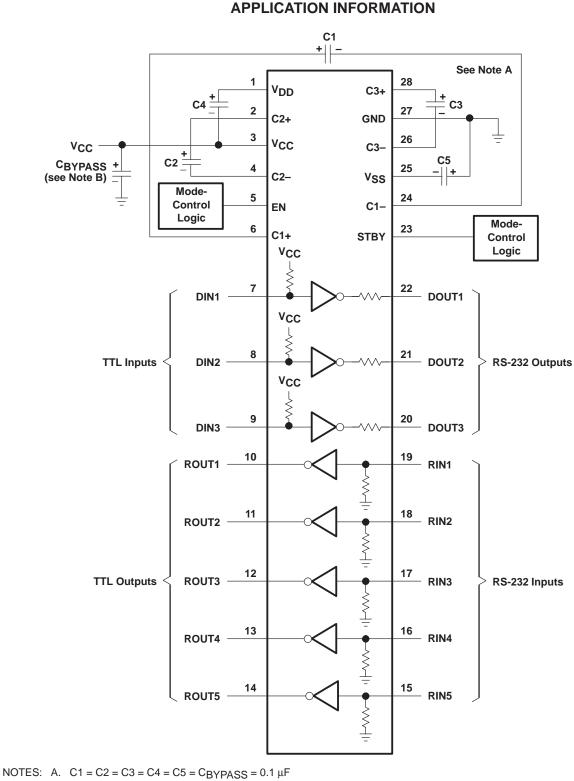
NOTES: A. CL includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 1 MHz,  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_f \le 10$  ns.  $t_f \le 10$  ns.

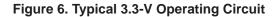
#### Figure 5. Receiver Enable and Disable Times



SLLS178D - APRIL 1994 - REVISED FEBRUARY 2000

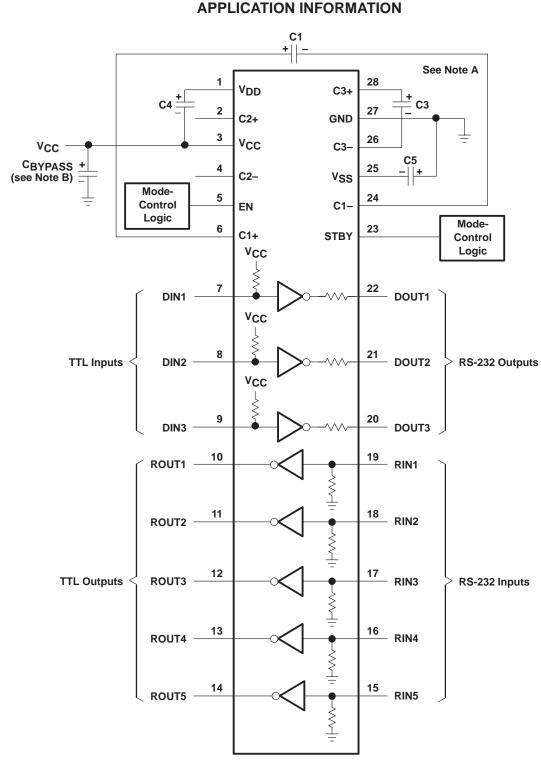


B. CBYPASS is used as a decoupling capacitor.



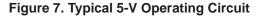


SLLS178D - APRIL 1994 - REVISED FEBRUARY 2000



NOTES: A. C2 is not used. C1 = C3 = C4 = C5 = C<sub>BYPASS</sub> = 0.1  $\mu$ F

B. C<sub>BYPASS</sub> is used as a decoupling capacitor.





V IEXAS

#### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN75LV4737ADB	ACTIVE	SSOP	DB	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LV4737ADBE4	ACTIVE	SSOP	DB	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LV4737ADBG4	ACTIVE	SSOP	DB	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LV4737ADBLE	OBSOLETE	SSOP	DB	28		TBD	Call TI	Call TI
SN75LV4737ADBR	ACTIVE	SSOP	DB	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LV4737ADBRE4	ACTIVE	SSOP	DB	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LV4737ADBRG4	ACTIVE	SSOP	DB	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined. **Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered

at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

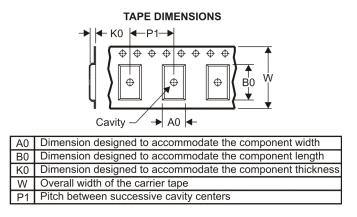
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## TAPE AND REEL INFORMATION





## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal													
	Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	SN75LV4737ADBR	SSOP	DB	28	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



# PACKAGE MATERIALS INFORMATION

11-Mar-2008



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75LV4737ADBR	SSOP	DB	28	2000	346.0	346.0	33.0

# **MECHANICAL DATA**

MSSO002E - JANUARY 1995 - REVISED DECEMBER 2001

## DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



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